

SLOTOCOUP ME 2150 电镀铜系统

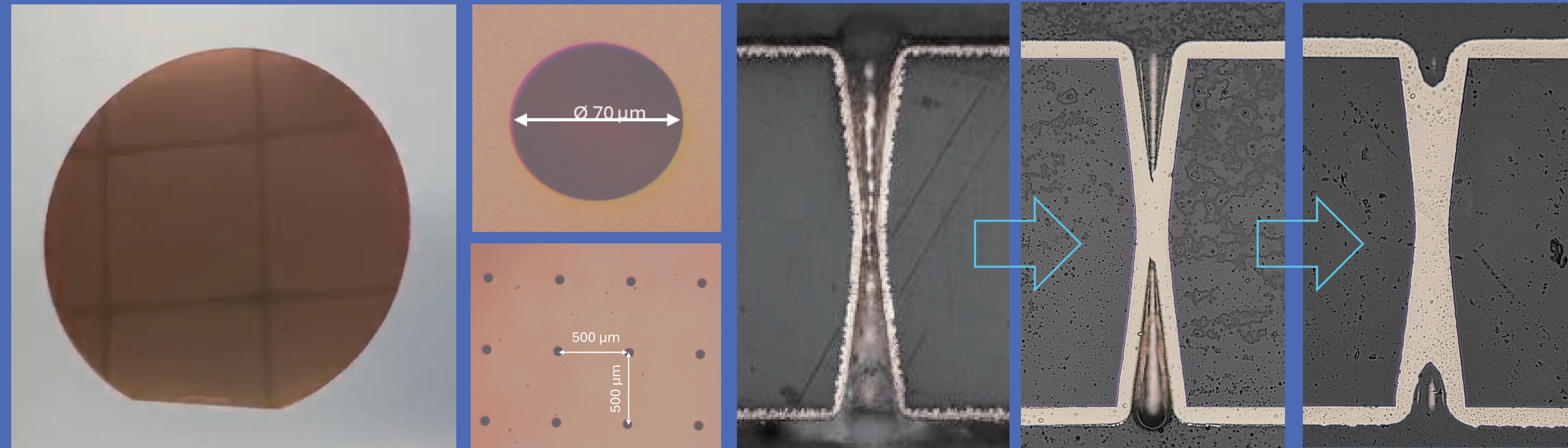
适合玻璃基板的电镀铜系统

High depositing speed / High current Reverse Pulse Plating technology

为了应对 FOPLP 及 Interposer 市场的蓬勃发展,施洛特全新研发了电镀沉积铜产品 SLOTOCOUP ME 2150。该产品拥有卓越的填孔能力与孔内铜复盖能力,特别适用于 TGV (通孔导体)产品,确保更高效的制程与更优秀的电镀性能。

To meet increasing demand from the FOPLP and Interposer markets, Schlötter has recently developed SLOTOCOUP ME 2150: an electroplated copper electrolyte product. This product has excellent via-filling capabilities and copper coverage inside holes, making it particularly suitable for TGV (Through Glass Via) products, ensuring a more efficient process and superior electrical performance.

产品优势 Benefits



Ø70mm, PP400um (AR5.7)

THK 14um

应用领域 Application

- FOPLP封装
Fan out panel level package
- IC interposer
- Hyper speed server and communication server
- IC重布线层(RDL)
Redistribution layer (RDL)

CO₂足迹 CO₂ Footprint

